

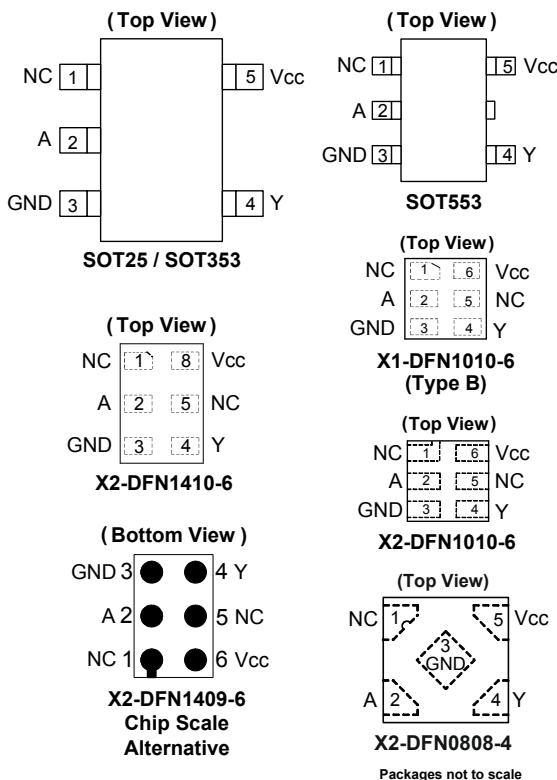
Description

The 74LVC1G34 is a single buffer gate with a standard push-pull output. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down.

The gate performs the positive Boolean function:

$$Y = A$$

Pin Assignments



Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- $\pm 24\text{mA}$ Output Drive at 3.3V
- CMOS Low Power Consumption
- I_{OFF} Supports Partial-Power-Down Mode Operation
- Inputs Accept Up to 5.5V
- ESD Protection Tested per JESD 22
 - Exceeds 2000-V Human Body Model (A114)
 - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Range of Package Options
- Direct Interface with TTL Levels
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative.
<https://www.diodes.com/quality/product-definitions/>
- An Automotive-Compliant Part is Available Under Separate Datasheet ([74LVC1G34Q](#))

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

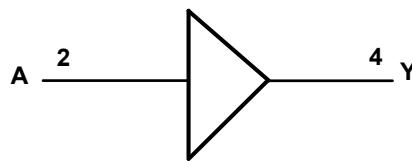
Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products such as:
 - PCs, Networking, Notebooks, Netbooks, PDAs
 - Tablet Computers, E-Readers
 - Computer Peripherals, Hard Drives, CD/DVD ROMs
 - TVs, DVDs, DVRs, Set-Top Boxes
 - Cell Phones, Personal Navigation / GPS
 - MP3 Players, Cameras, Video Recorders

Pin Descriptions

Pin Name	Description
NC	No Connection
A	Data Input
GND	Ground
Y	Data Output
V _{CC}	Supply Voltage

Logic Diagram



Function Table

Input	Output
A	Y
H	H
L	L

Absolute Maximum Ratings (Notes 4 & 5) (@ T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
V _I	Input Voltage Range	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High Impedance or I _{OFF} State	-0.5 to 6.5	V
V _O	Voltage Applied to Output in High or Low State	-0.5 to V _{CC} + 0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
I _{OK}	Output Clamp Current	-50	mA
I _O	Continuous Output Current	±50	mA
I _{CC} , I _{GN}	Continuous Current Through V _{CC} or GND	±100	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{TSG}	Storage Temperature	-65 to +150	°C

Notes:

- 4. Stresses beyond the absolute maximum can result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
- 5. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 6) (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Symbol	Parameter		Min	Max	Unit
V_{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data Retention Only	1.5	—	V
V_{IH}	High-Level Input Voltage	$V_{CC} = 1.65\text{V}$ to 1.95V	$0.65 \times V_{CC}$	—	V
		$V_{CC} = 2.3\text{V}$ to 2.7V	1.7	—	
		$V_{CC} = 3\text{V}$ to 3.6V	2	—	
		$V_{CC} = 4.5\text{V}$ to 5.5V	$0.7 \times V_{CC}$	—	
V_{IL}	Low-Level Input Voltage	$V_{CC} = 1.65\text{V}$ to 1.95V	—	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{V}$ to 2.7V	—	0.7	
		$V_{CC} = 3\text{V}$ to 3.6V	—	0.8	
		$V_{CC} = 4.5\text{V}$ to 5.5V	—	$0.3 \times V_{CC}$	
V_I	Input Voltage		0	5.5	V
V_O	Output Voltage		0	V_{CC}	V
I_{OH}	High-Level Output Current	$V_{CC} = 1.65\text{V}$	—	-4	mA
		$V_{CC} = 2.3\text{V}$	—	-8	
		$V_{CC} = 2.7\text{V}$	—	-12	
		$V_{CC} = 3\text{V}$	—	-16	
		$V_{CC} = 4.5\text{V}$	—	-24	
		$V_{CC} = 4.5\text{V}$	—	-32	
I_{OL}	Low-Level Output Current	$V_{CC} = 1.65\text{V}$	—	4	mA
		$V_{CC} = 2.3\text{V}$	—	8	
		$V_{CC} = 2.7\text{V}$	—	-12	
		$V_{CC} = 3\text{V}$	—	16	
		$V_{CC} = 4.5\text{V}$	—	24	
		$V_{CC} = 4.5\text{V}$	—	32	
$\Delta t/\Delta V$	Input Transition Rise or Fall Rate	$V_{CC} = 1.8\text{V} \pm 0.15\text{V}, 2.5\text{V} \pm 0.2\text{V}$	—	20	ns/V
		$V_{CC} = 3.3\text{V} \pm 0.3\text{V}$	—	10	
		$V_{CC} = 5\text{V} \pm 0.5\text{V}$	—	5	
T_A	Operating Free-Air Temperature		-40	+125	°C

Note: 6. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^\circ C$.)

Symbol	Parameter	Test Conditions	V_{CC}	-40°C to +85°C			-40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
V_{OH}	High Level Output Voltage	$I_{OH} = -100\mu A$	1.65V to 5.5V	$V_{CC} - 0.1$	—	—	$V_{CC} - 0.1$	—	V
		$I_{OH} = -4mA$	1.65V	1.2	—	—	0.95	—	
		$I_{OH} = -8mA$	2.3V	1.9	—	—	1.7	—	
		$I_{OH} = -12mA$	2.7V	2.2	—	—	1.9	—	
		$I_{OH} = -16mA$	3V	2.4	—	—	2.2	—	
		$I_{OH} = -24mA$		2.3	—	—	2.0	—	
		$I_{OH} = -32mA$	4.5V	3.8	—	—	3.4	—	
V_{OL}	Low Level Output Voltage	$I_{OL} = 100\mu A$	1.65V to 5.5V	—	—	0.1	—	0.1	V
		$I_{OL} = 4mA$	1.65V	—	—	0.45	—	0.7	
		$I_{OL} = 8mA$	2.3V	—	—	0.3	—	0.45	
		$I_{OL} = 12mA$	2.7V	—	—	0.4	—	0.6	
		$I_{OL} = 16mA$	3V	—	—	0.4	—	0.6	
		$I_{OL} = 24mA$		—	—	0.55	—	0.8	
		$I_{OL} = 32mA$	4.5V	—	—	0.55	—	0.8	
I_I	Input Current	$V_I = 5.5V$ or GND	0V to 5.5V	—	± 0.1	± 1	—	± 2	μA
I_{OFF}	Power Down Leakage Current	V_I or $V_O = 5.5V$	0V	—	—	± 10	—	± 10	μA
I_{CC}	Supply Current	$V_I = 5.5V$ or GND, $I_O = 0$	5.5V	—	0.1	1	—	10	μA
ΔI_{CC}	Additional Supply Current	Input at $V_{CC} - 0.6V$	3V to 5.5V	—	—	500	—	500	μA
C_I	Input Capacitance	$V_I = V_{CC}$ or GND	3.3V	—	5	—	—	—	pF

Package Characteristics

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ	Max	Unit
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT25	(Note 7)	—	204	—	°C/W
		SOT353		—	371	—	
		SOT553		—	231	—	
		X2-DFN0808-4		—	400	—	
		X1-DFN1010-6 (Type B)		—	435	—	
		X2-DFN1010-6		—	445	—	
		X2-DFN1409-6		—	470	—	
		X2-DFN1410-6		—	460	—	
θ_{JC}	Thermal Resistance Junction-to-Case	SOT25	(Note 7)	—	52	—	°C/W
		SOT353		—	143	—	
		SOT553		—	105	—	
		X2-DFN0808-4		—	225	—	
		X1-DFN1010-6 (Type B)		—	250	—	
		X2-DFN1010-6		—	250	—	
		X2-DFN1409-6		—	275	—	
		X2-DFN1410-6		—	265	—	

Note: 7. Test condition for each of the 8 package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

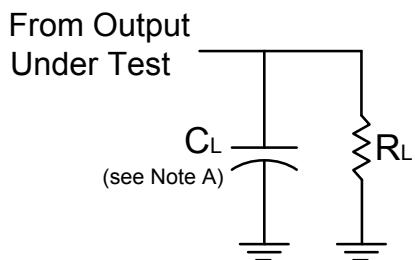
Switching Characteristics (Figure 1, Typical Values at $T_A = +25^\circ\text{C}$ and Nominal Voltages 1.8V, 2.5V, 3.3V, and 5.0V.)

Parameter	From Input	To Output	V _{CC}	T _A = -40°C to +85°C			T _A = -40°C to +125°C		Unit
				Min	Typ	Max	Min	Max	
t _{PD}	A or B	Y	1.8V ± 0.15V	1.0	3.0	7.5	1.0	9.5	ns
			2.5V ± 0.2V	0.5	2.0	5.0	0.5	6.5	
			2.7V	0.5	2.3	5.2	0.5	7.0	
			3.3V ± 0.3V	0.5	2.0	4.2	0.5	5.5	
			5.0V ± 0.5V	0.5	1.6	3.7	0.5	5.0	

Operating Characteristics (All typical values are at V_{CC} = 3.3V, T_A = +25°C.)

Parameter	Test Conditions	V _{CC} = 1.8V	V _{CC} = 2.5V	V _{CC} = 3.3V	V _{CC} = 5V	Unit
		Typ	Typ	Typ	Typ	
C _{PD}	Power Dissipation Capacitance	f = 10MHz	16	16	16	16 pF

Parameter Measurement Information



V _{CC}	Inputs		V _M	C _L	R _L
	V _I	t _R /t _F			
1.8V ± 0.15V	V _{CC}	≤2ns	V _{CC} /2	30pF	1kΩ
2.5V ± 0.2V	V _{CC}	≤2ns	V _{CC} /2	30pF	500Ω
2.7V	V _{CC}	≤2.5ns	1.5V	50pF	500Ω
3.3V ± 0.3V	3.0V	≤2.5ns	1.5V	50pF	500Ω
5.0V ± 0.5V	V _{CC}	≤2.5ns	V _{CC} /2	50pF	500Ω

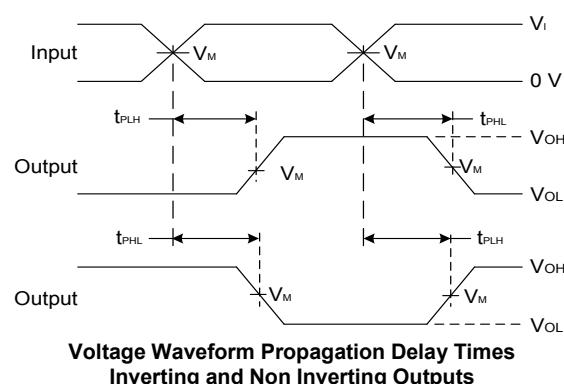
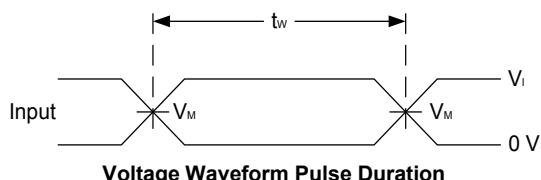
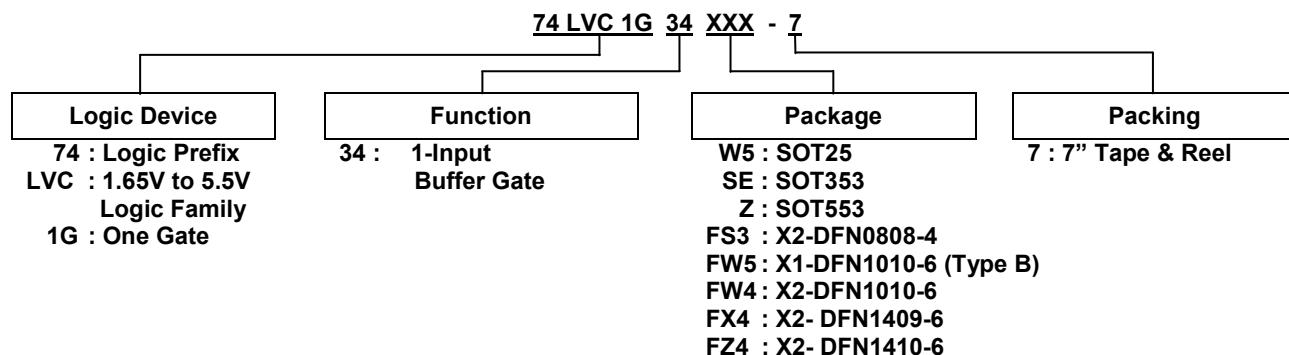


Figure 1. Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 10MHz.
 - C. t_{PLH} and t_{PHL} are the same as t_{PD}.

Ordering Information (Note 8)

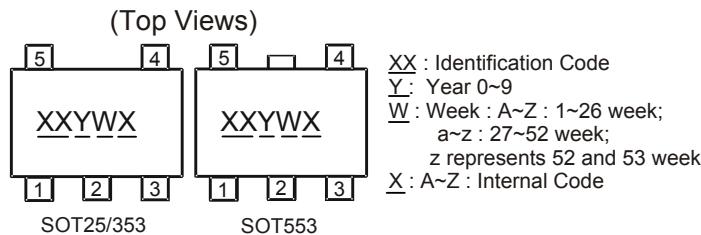


Part Number	Package Code	Package (Notes 9 & 10)	7" Tape and Reel	
			Quantity	Part Number Suffix
74LVC1G34W5-7	W5	SOT25	3,000/Tape & Reel	-7
74LVC1G34SE-7	SE	SOT353	3,000/Tape & Reel	-7
74LVC1G34Z-7	Z	SOT553	4,000/Tape & Reel	-7
74LVC1G34FS3-7	FS3	X2-DFN0808-4	5,000/Tape & Reel	-7
74LVC1G34FW5-7	FW5	X1-DFN1010-6 (Type B)	5,000/Tape & Reel	-7
74LVC1G34FW4-7	FW4	X2-DFN1010-6	5,000/Tape & Reel	-7
74LVC1G34FX4-7	FX4	X2-DFN1409-6 (Chip Scale Alternative)	5,000/Tape & Reel	-7
74LVC1G34FZ4-7	FZ4	X2-DFN1410-6	5,000/Tape & Reel	-7

- Notes:
- 8. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.
 - 9. Pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at <http://www.diodes.com/package-outlines.html>.
 - 10. The taping orientation is located on our website at <https://www.diodes.com/assets/Packaging-Support-Docs/ap02007.pdf>.

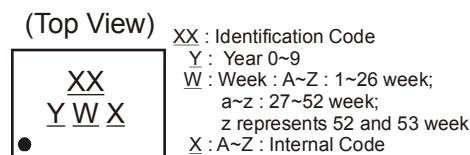
Marking Information

(1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G34W5-7	SOT25	UK
74LVC1G34SE-7	SOT353	UK
74LVC1G34Z-7	SOT553	UK

(2) DFN Packages

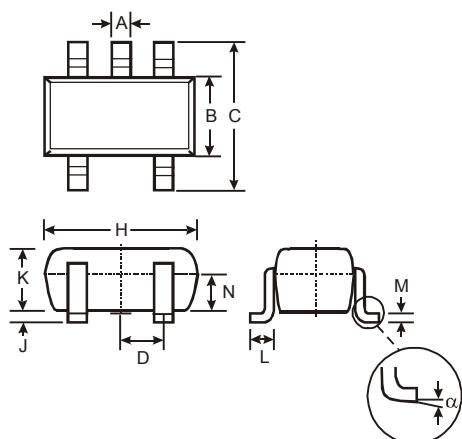


Part Number	Package	Identification Code
74LVC1G34FS3-7	X2-DFN0808-4	YV
74LVC1G34FW5-7	X1-DFN1010-6 (Type B)	VW
74LVC1G34FW4-7	X2-DFN1010-6	UK
74LVC1G34FX4-7	X2-DFN1409-6	MK
74LVC1G34FZ4-7	X2-DFN1410-6	UK

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

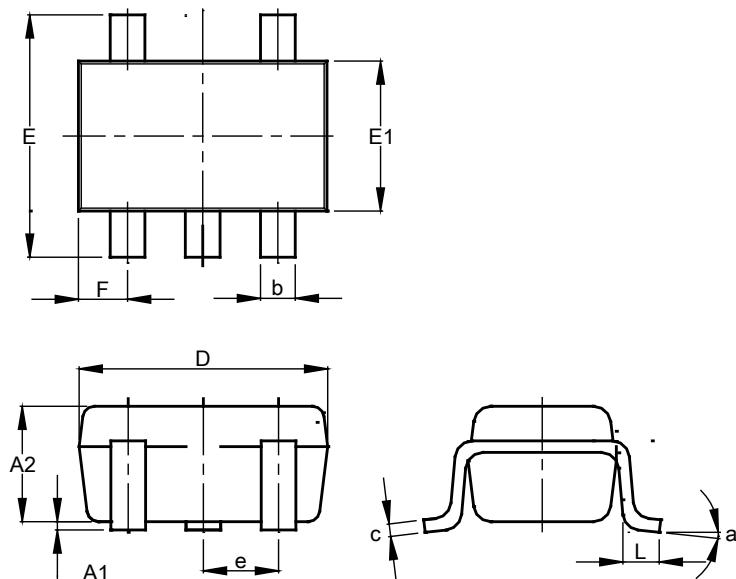
(1) Package Type: SOT25



SOT25			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-

All Dimensions in mm

(2) Package Type: SOT353



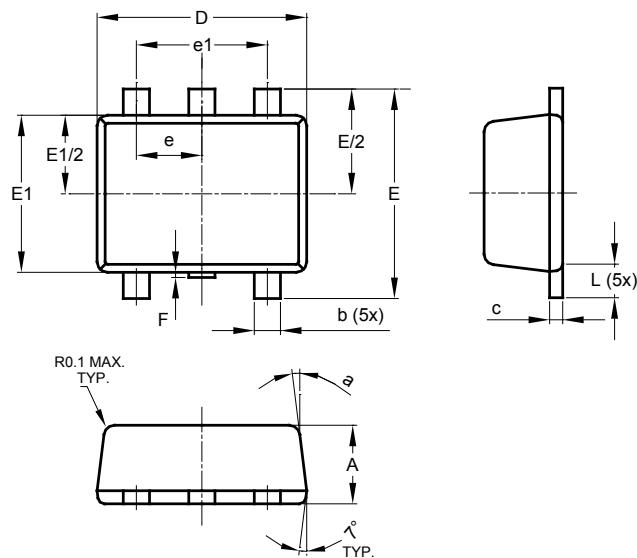
SOT353			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	0.95
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--

All Dimensions in mm

Package Outline Dimensions (continued)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

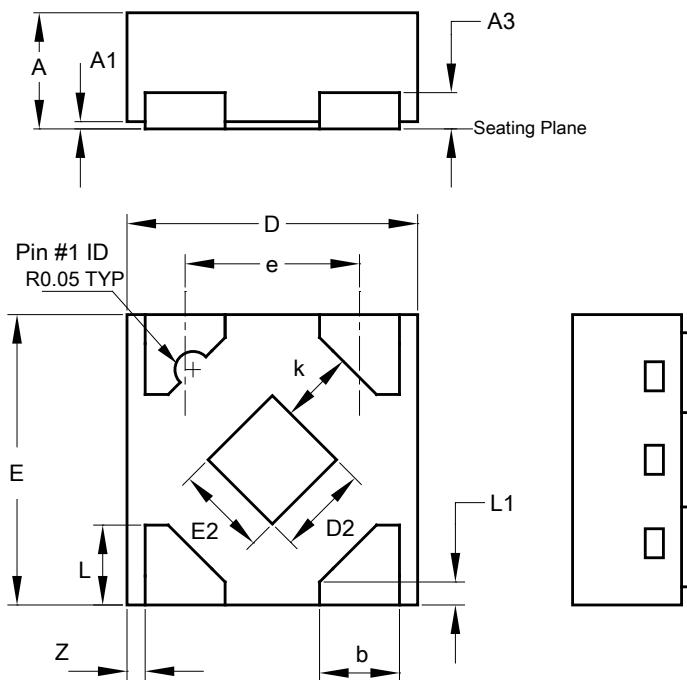
(3) Package Type: SOT553



SOT553			
Dim	Min	Max	Typ
A	0.55	0.62	0.60
b	0.15	0.30	0.20
c	0.10	0.18	0.15
D	1.50	1.70	1.60
E	1.55	1.70	1.60
E1	1.10	1.25	1.20
e	0.50 BSC		
e1	1.00 BSC		
F	0.00	0.10	—
L	0.10	0.30	0.20
a	6°	8°	7°

All Dimensions in mm

(4) Package Type: X2-DFN0808-4



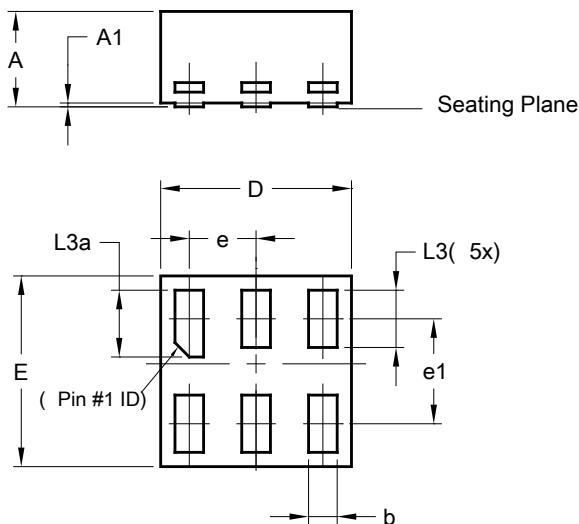
X2-DFN0808-4			
Dim	Min	Max	Typ
A	0.25	0.35	0.30
A1	0	0.04	0.02
A3	-	-	0.13
b	0.17	0.27	0.22
D	0.75	0.85	0.80
D2	0.15	0.35	0.25
E	0.75	0.85	0.80
E2	0.15	0.35	0.25
e	-	-	0.48
k	0.20	-	-
L	0.17	0.27	0.22
L1	0.02	0.12	0.07
z	-	-	0.05

All Dimensions in mm

Package Outline Dimensions (continued)

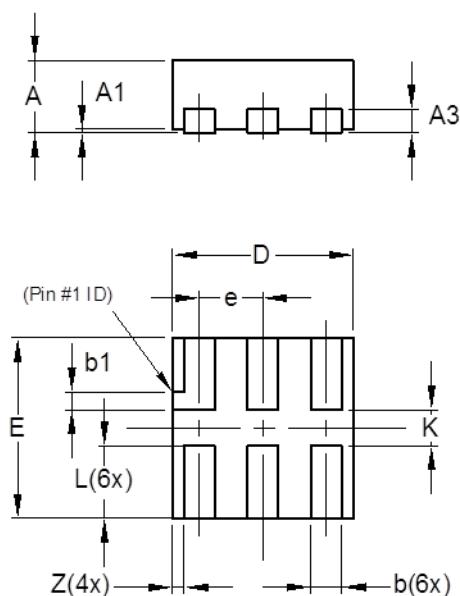
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(5) Package Type: X1-DFN1010-6 (Type B)



X1-DFN1010-6 (Type B)			
Dim	Min	Max	Typ
A	-	0.50	0.39
A1	-	0.04	-
b	0.12	0.20	0.15
D	0.95	1.050	1.00
E	0.95	1.050	1.00
e	0.35 BSC		
e1	0.55 BSC		
L3	0.27	0.30	0.30
L3a	0.32	0.40	0.35
All Dimensions in mm			

(6) Package Type: X2-DFN1010-6

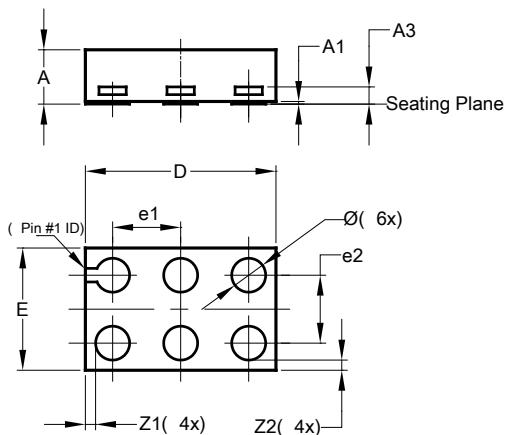


X2-DFN1010-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

Package Outline Dimensions (continued)

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

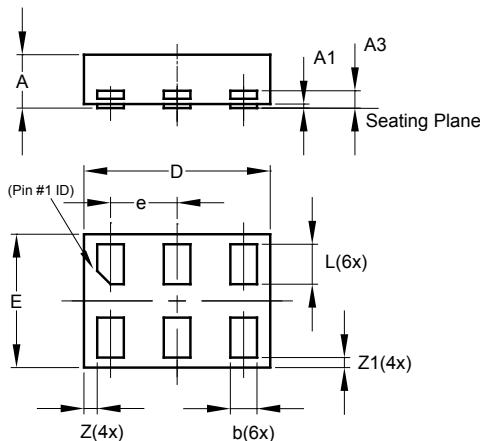
(7) Package Type: X2-DFN1409-6



X2-DFN1409-6			
Dim	Min	Max	Typ
A	-	0.40	0.39
A1	0	0.05	0.02
A3	-	-	0.13
Ø	0.20	0.30	0.25
D	1.35	1.45	1.40
E	0.85	0.95	0.90
e1	-	-	0.50
e2	-	-	0.50
Z1	-	-	0.075
Z2	-	-	0.075

All Dimensions in mm

(8) Package Type: X2-DFN1410-6



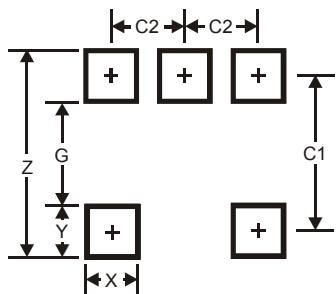
X2-DFN1410-6			
Dim	Min	Max	Typ
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075

All Dimensions in mm

Suggested Pad Layout

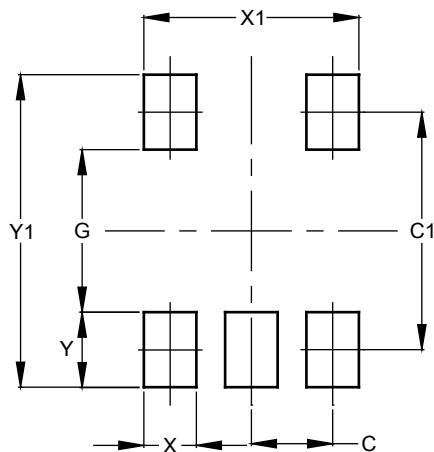
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(1) Package Type: SOT25



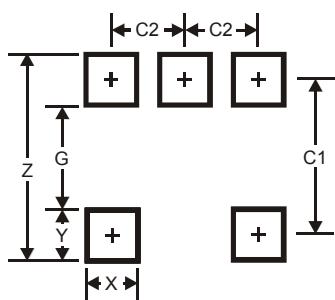
Dimensions	Value
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

(2) Package Type: SOT353



Dimensions	Value (in mm)
C	0.650
C1	1.900
G	1.300
X	0.420
X1	1.720
Y	0.600
Y1	2.500

(3) Package Type: SOT553

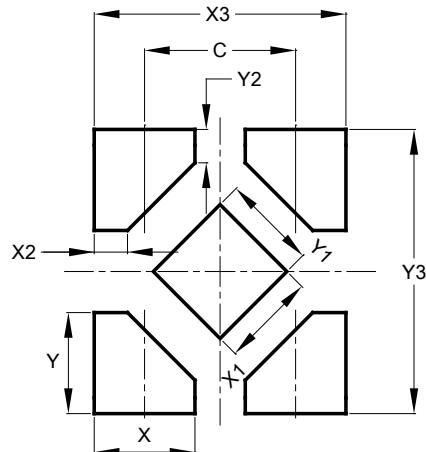


Dimensions	Value
Z	2.2
G	1.2
X	0.375
Y	0.5
C1	1.7
C2	0.5

Suggested Pad Layout (continued)

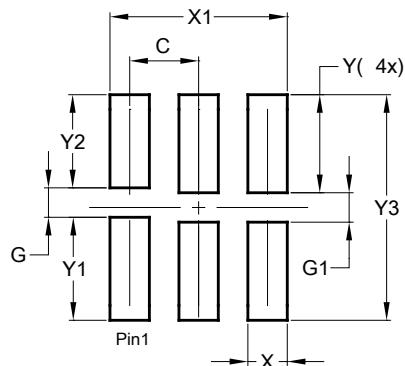
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(4) Package Type: X2-DFN0808-4



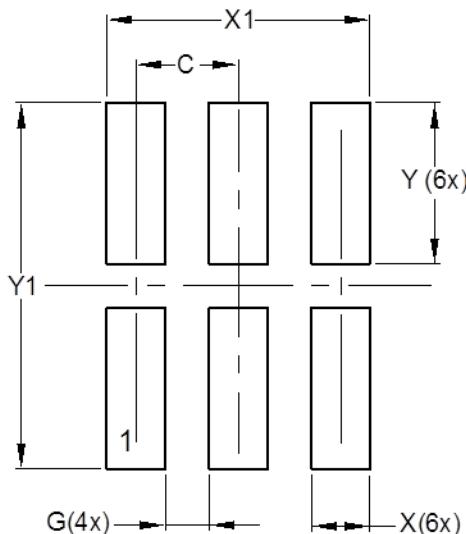
Dimensions	Value
C	0.480
X	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900

(5) Package Type: X1-DFN1010-6 (Type B)



Dimensions	Value (in mm)
C	0.350
G	0.150
G1	0.150
X	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

(6) Package Type: X2-DFN1010-6

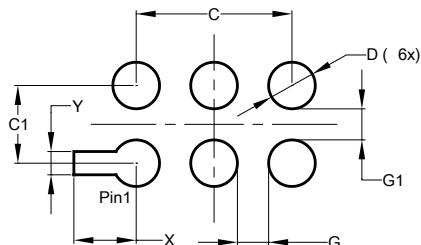


Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

Suggested Pad Layout (continued)

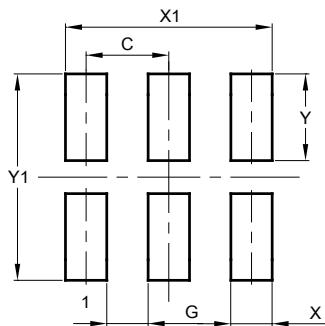
Please see <http://www.diodes.com/package-outlines.html> for the latest version.

(7) Package Type: X2-DFN1409-6



Dimensions	Value (in mm)
C	1.000
C1	0.500
D	0.300
G	0.200
G1	0.200
X	0.400
Y	0.150

(8) Package Type: X2-DFN1410-6



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

Mechanical Data

SOT25

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Mate Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ^(e3)
- Weight: 0.016 grams (Approximate)

SOT353

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Mate Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ^(e3)
- Weight: 0.006 grams (Approximate)

SOT553

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Mate Tin Plated Leads, Solderable per MIL-STD-202, Method 208 ^(e3)
- Weight: 0.003 grams (Approximate)

X2-DFN0808-4

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.001 grams (Approximate)

X1-DFN1010-6 (Type B)

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.001 grams (Approximate)

X2-DFN1010-6

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.001 grams (Approximate)

X2-DFN1409-6

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.002 grams (Approximate)

X2-DFN1410-6

- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - NiPdAu Nickel Palladium Gold, Solderable per MIL-STD-202, Method 208 ^(e4)
- Weight: 0.002 grams (Approximate)

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